

What is claimed is:

1. A method of manufacturing a semiconductor device, comprising the steps of:
  - 5 forming a gate oxide over a substrate;
  - depositing a first layer of silicon over the gate oxide;
  - implanting dopants into the first layer;
  - depositing a second layer of silicon over the first layer;
  - etching the first and second layers to form a gate electrode;
  - implanting dopants within the substrate to form source/drain regions in the substrate; and
  - melting at least the first layer by laser thermal annealing.
2. The method of manufacturing a semiconductor device according to claim 1, wherein the first layer has a depth of about 200 to 500 angstroms.
3. The method of manufacturing a semiconductor device according to claim 2, wherein the second layer has a depth of about 300 to 4500 angstroms.
4. The method of manufacturing a semiconductor device according to claim 1, wherein said step of implanting dopants in the first layer amorphitizes the first layer.
5. The method of manufacturing a semiconductor device according to claim 1, wherein said step of implanting dopants to form the source/drain regions implants dopants into the second layer and amorphitizes at least a portion of the second layer.
6. The method of manufacturing a semiconductor device according to claim 5, wherein said step of melting the first layer also melts the amorphitized portion of the second layer.
7. The method of manufacturing a semiconductor device according to claim 1, wherein the first layer is doped at a concentration higher than a solubility limit of the dopants in the first layer.
8. The method of manufacturing a semiconductor device according to claim 1, further comprising the steps of forming source/drain extensions in the substrate adjacent to the gate electrode and forming sidewall spacers adjacent to the gate electrode.

9. The method of manufacturing a semiconductor device according to claim 8, wherein the source/drain extensions have a depth of about 50 to 300 angstroms.

10. The method of manufacturing a semiconductor device according to claim 1, wherein the source/drain regions have a depth of about 400 to 1000 angstroms.

11. The method of manufacturing a semiconductor device according to claim 1, wherein the laser thermal annealing activates the source/drain regions.

12. The method of manufacturing a semiconductor device according to claim 1, wherein the semiconductor device is a MOSFET.

13. A method of manufacturing a MOSFET semiconductor device, comprising the steps of:  
forming a gate oxide over a substrate;  
depositing a first layer of silicon over the gate oxide to a depth of about 200 to 500  
angstroms;

implanting dopants into the first layer at a concentration higher than a solubility limit of  
the dopants in the first layer;

depositing a second layer of silicon over the first layer to a depth of about 300 to 4500  
angstroms;

etching the first and second layers to form a gate electrode;  
forming source/drain extensions in the substrate adjacent to the gate electrode to a depth  
of about 50 to 300 angstroms;

implanting dopants within the substrate to form amorphitized source/drain regions in the  
substrate adjacent to the sidewall spacers to a depth of about 400 to 1000 angstroms and to  
amorphitize at least a portion of the second layer; and

15 melting the amorphitized first and second layers by laser thermal annealing,  
wherein the laser thermal annealing activates the source/drain regions.

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